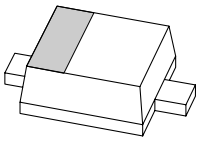


PMEG2010AEJ

20 V, 1 A very low V_F MEGA Schottky barrier rectifier in SOD323F package

Rev. 03 — 15 January 2010 Product data sheet

1. Product profile

1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD323F (SC-90) very small and flat lead Surface Mounted Device (SMD) plastic package.

1.2 Features

- Forward current: ≤ 1 A
- Reverse voltage: ≤ 20 V
- Very low forward voltage
- Very small and flat lead SMD plastic package

1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Inverse polarity protection
- Low power consumption applications

1.4 Quick reference data

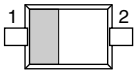
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I_F	forward current	$T_{sp} \leq 55$ °C		-	-	1	A
V_R	reverse voltage			-	-	20	V
V_F	forward voltage	I_F = 1000 mA	[1]	-	480	550	mV

[1] Pulse test: $t_p \leq 300$ μs; $\delta \leq 0.02$.

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	cathode [1]		 sym001
2	anode		

[1] The marking bar indicates the cathode.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG2010AEJ	SC-90	plastic surface mounted package; 2 leads	SOD323F

4. Marking

Table 4. Marking codes

Type number	Marking code
PMEG2010AEJ	EM

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage			-	20	V
I_F	forward current	$T_{sp} \leq 55$ °C		-	1	A
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ ms; $\delta \leq 0.25$		-	5.5	A
I_{FSM}	non-repetitive peak forward current	square wave; $t_p = 8$ ms		-	10	A
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1]	-	360	mW
			[2]	-	830	mW
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			−65	+150	°C
T_{stg}	storage temperature			−65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]	-	-	350	K/W
			[1][3]	-	-	150	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	55	K/W

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses. Nomograms for determining the reverse power losses P_R and $I_{F(AV)}$ rating are available on request.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2.

[4] Solder point of cathode tab.

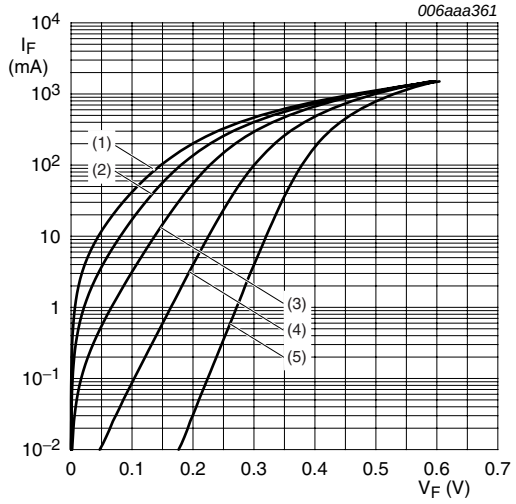
7. Characteristics

Table 7. Characteristics

T_{amb} = 25 °C unless otherwise specified.

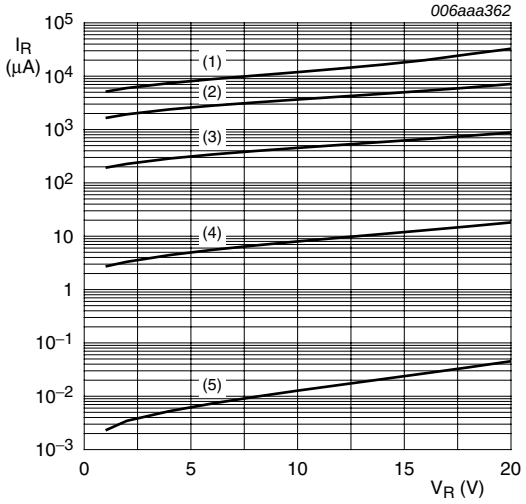
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_F	forward voltage		[1]				
		I_F = 10 mA		-	240	270	mV
		I_F = 100 mA		-	300	350	mV
		I_F = 500 mA		-	400	460	mV
		I_F = 1000 mA		-	480	550	mV
I_R	reverse current	V_R = 5 V		-	5	10	µA
		V_R = 8 V		-	7	20	µA
		V_R = 10 V		-	8	30	µA
		V_R = 15 V		-	10	50	µA
		V_R = 20 V		-	15	70	µA
C_d	diode capacitance	V_R = 1 V; f = 1 MHz		-	40	50	pF

[1] Pulse test: $t_p \leq 300$ µs; $\delta \leq 0.02$.



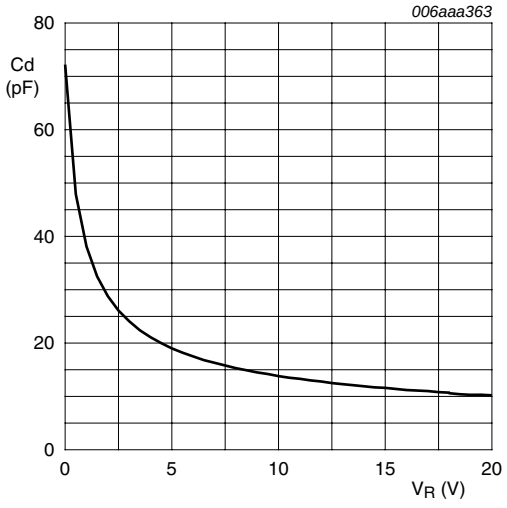
(1) T_{amb} = 150 °C
(2) T_{amb} = 125 °C
(3) T_{amb} = 85 °C
(4) T_{amb} = 25 °C
(5) T_{amb} = −40 °C

Fig 1. Forward current as a function of forward voltage; typical values



(1) T_{amb} = 150 °C
(2) T_{amb} = 125 °C
(3) T_{amb} = 85 °C
(4) T_{amb} = 25 °C
(5) T_{amb} = −40 °C

Fig 2. Reverse current as a function of reverse voltage; typical values



T_{amb} = 25 °C; f = 1 MHz

Fig 3. Diode capacitance as a function of reverse voltage; typical values

8. Package outline

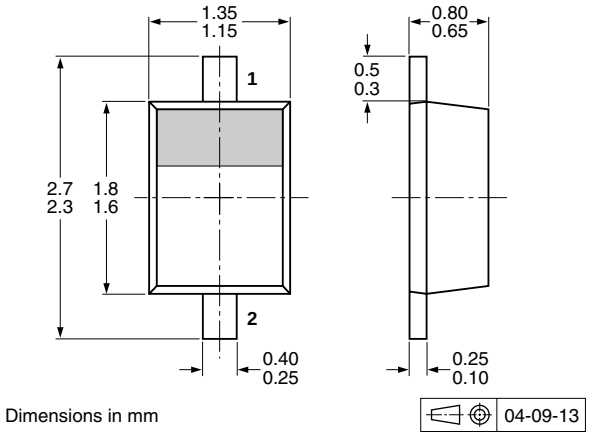


Fig 4. Package outline SOD323F (SC-90)

9. Packing information

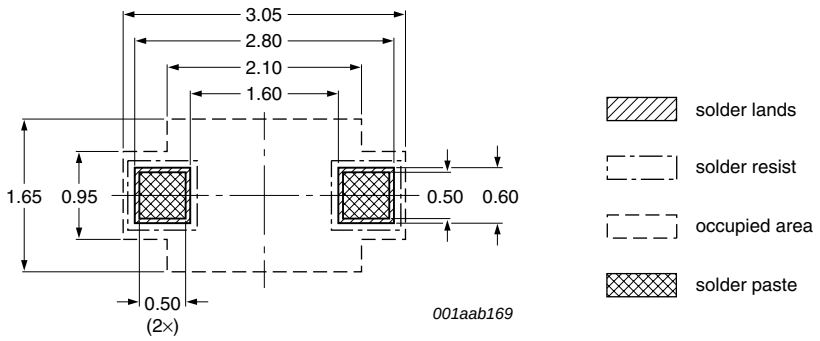
Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number	Package	Description	Packing quantity	
			3000	10000
PMEG2010AEJ	SOD323F	4 mm pitch, 8 mm tape and reel	-115	-135

[1] For further information and the availability of packing methods, see Section 14.

10. Soldering

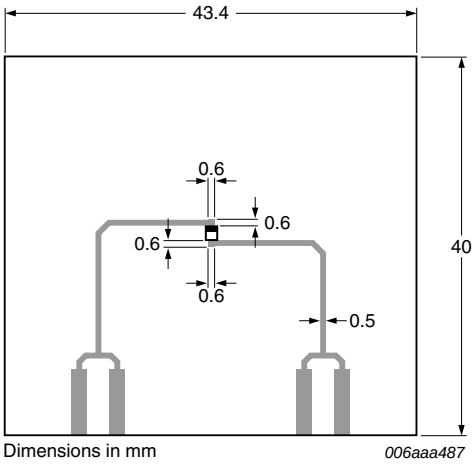


Reflow soldering is the only recommended soldering method.

Dimensions in mm

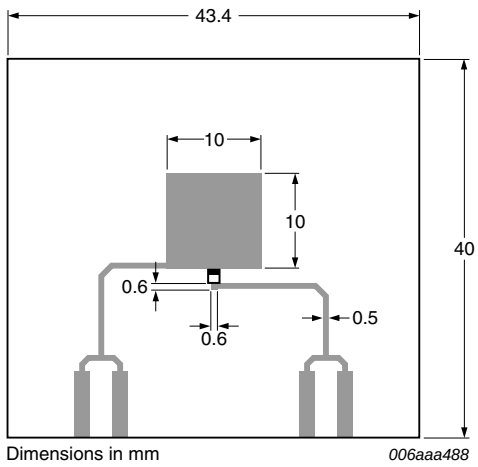
Fig 5. Reflow soldering footprint SOD323F (SC-90)

11. Mounting



PCB thickness: d = 1.6 mm

Fig 6. FR4 PCB, standard footprint SOD323F (SC-90)



PCB thickness: d = 1.6 mm

Fig 7. FR4 PCB, mounting pad for cathode 1 cm^2 SOD323F (SC-90)

12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMEG2010AEJ_3	20100115	Product data sheet	-	PMEG2010AEJ_2
Modifications:	• This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.			
PMEG2010AEJ_2	20051014	Product data sheet	-	PMEG2010AEJ_1
PMEG2010AEJ_1	20050302	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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15. Contents

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